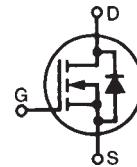


# X-Class HiPERFET Power MOSFET

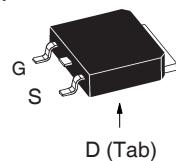
**IXFY4N85X**  
**IXFA4N85X**  
**IXFP4N85X**

**V<sub>DSS</sub>** = 850V  
**I<sub>D25</sub>** = 3.5A  
**R<sub>DS(on)</sub>** ≤ 2.5Ω

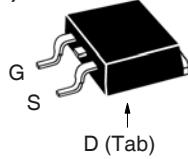
N-Channel Enhancement Mode



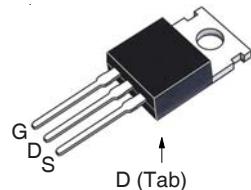
TO-252 (IXFY)



TO-263 (IXFA)



TO-220 (IXFP)



G = Gate      D = Drain  
S = Source      Tab = Drain

Symbol	Test Conditions	Maximum Ratings	
V <sub>DSS</sub>	T <sub>J</sub> = 25°C to 150°C	850	V
V <sub>DGR</sub>	T <sub>J</sub> = 25°C to 150°C, R <sub>GS</sub> = 1MΩ	850	V
V <sub>GSS</sub>	Continuous	±30	V
V <sub>GSM</sub>	Transient	±40	V
I <sub>D25</sub>	T <sub>C</sub> = 25°C	3.5	A
I <sub>DM</sub>	T <sub>C</sub> = 25°C, Pulse Width Limited by T <sub>JM</sub>	10.0	A
I <sub>A</sub>	T <sub>C</sub> = 25°C	2	A
E <sub>AS</sub>	T <sub>C</sub> = 25°C	125	mJ
dv/dt	I <sub>S</sub> ≤ I <sub>DM</sub> , V <sub>DD</sub> ≤ V <sub>DSS</sub> , T <sub>J</sub> ≤ 150°C	50	V/ns
P <sub>D</sub>	T <sub>C</sub> = 25°C	150	W
T <sub>J</sub>		-55 ... +150	°C
T <sub>JM</sub>		150	°C
T <sub>stg</sub>		-55 ... +150	°C
T <sub>L</sub>	Maximum Lead Temperature for Soldering	300	°C
T <sub>SOLD</sub>	1.6 mm (0.062in.) from Case for 10s	260	°C
F <sub>c</sub>	Mounting Force (TO-263)	10..65 / 2.2..14.6	N/lb
M <sub>d</sub>	Mounting Torque (TO-220)	1.13 / 10	Nm/lb.in
Weight	TO-252	0.35	g
	TO-263	2.50	g
	TO-220	3.00	g

Symbol	Test Conditions (T <sub>J</sub> = 25°C, Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max.
BV <sub>DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA	850		V
V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	3.0		V
I <sub>GSS</sub>	V <sub>GS</sub> = ±30V, V <sub>DS</sub> = 0V			±100 nA
I <sub>DSS</sub>	V <sub>DS</sub> = V <sub>DSS</sub> , V <sub>GS</sub> = 0V T <sub>J</sub> = 125°C			5 μA 500 μA
R <sub>DS(on)</sub>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 2A, Note 1			2.5 Ω

## Features

- International Standard Packages
- Low R<sub>DS(ON)</sub> and Q<sub>G</sub>
- Avalanche Rated
- Low Package Inductance

## Advantages

- High Power Density
- Easy to Mount
- Space Savings

## Applications

- Switch-Mode and Resonant-Mode Power Supplies
- DC-DC Converters
- PFC Circuits
- AC and DC Motor Drives
- Robotics and Servo Controls

Symbol	Test Conditions ( $T_J = 25^\circ\text{C}$ , Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max
$g_{fs}$	$V_{DS} = 10\text{V}$ , $I_D = 2\text{A}$ , Note 1	1.2	2.0	S
$R_{Gi}$	Gate Input Resistance		3	$\Omega$
$C_{iss}$ $C_{oss}$ $C_{rss}$	$V_{GS} = 0\text{V}$ , $V_{DS} = 25\text{V}$ , $f = 1\text{MHz}$	247 305 5		pF
<b>Effective Output Capacitance</b>				
$C_{o(er)}$ $C_{o(tr)}$	Energy related } $V_{GS} = 0\text{V}$ Time related } $V_{DS} = 0.8 \cdot V_{DSS}$	27 60		pF
$t_{d(on)}$ $t_r$ $t_{d(off)}$ $t_f$	$V_{GS} = 10\text{V}$ , $V_{DS} = 0.5 \cdot V_{DSS}$ , $I_D = 2\text{A}$ $R_G = 30\Omega$ (External)	13 27 28 20		ns
$Q_{g(on)}$ $Q_{gs}$ $Q_{gd}$	$V_{GS} = 10\text{V}$ , $V_{DS} = 0.5 \cdot V_{DSS}$ , $I_D = 2\text{A}$	7.0 2.3 3.3		nC
$R_{thJC}$ $R_{thCS}$	TO-220	0.50	0.83	$^\circ\text{C}/\text{W}$
				$^\circ\text{C}/\text{W}$

### Source-Drain Diode

Symbol	Test Conditions ( $T_J = 25^\circ\text{C}$ , Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max
$I_s$	$V_{GS} = 0\text{V}$		4	A
$I_{SM}$	Repetitive, pulse Width Limited by $T_{JM}$		16	A
$V_{SD}$	$I_F = I_S$ , $V_{GS} = 0\text{V}$ , Note 1		1.4	V
$t_{rr}$ $Q_{RM}$ $I_{RM}$	$I_F = 2\text{A}$ , $-di/dt = 100\text{A}/\mu\text{s}$ $V_R = 100\text{V}$	170 770 9		ns nC A

Note 1. Pulse test,  $t \leq 300\mu\text{s}$ , duty cycle,  $d \leq 2\%$ .

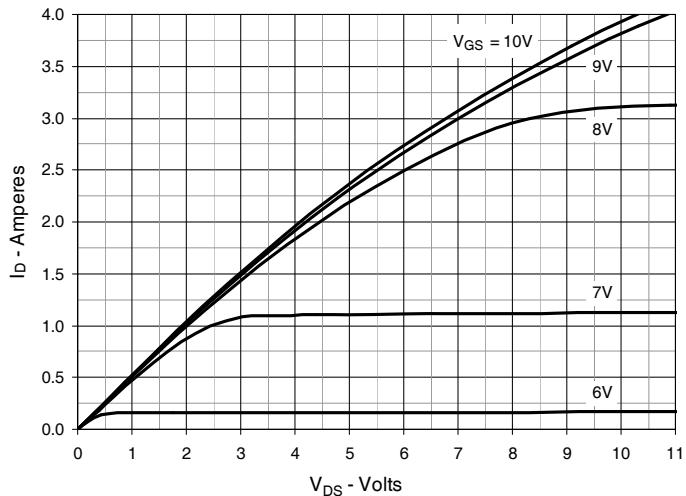
### PRELIMINARY TECHNICAL INFORMATION

The product presented herein is under development. The Technical Specifications offered are derived from a subjective evaluation of the design, based upon prior knowledge and experience, and constitute a "considered reflection" of the anticipated result. IXYS reserves the right to change limits, test conditions, and dimensions without notice.

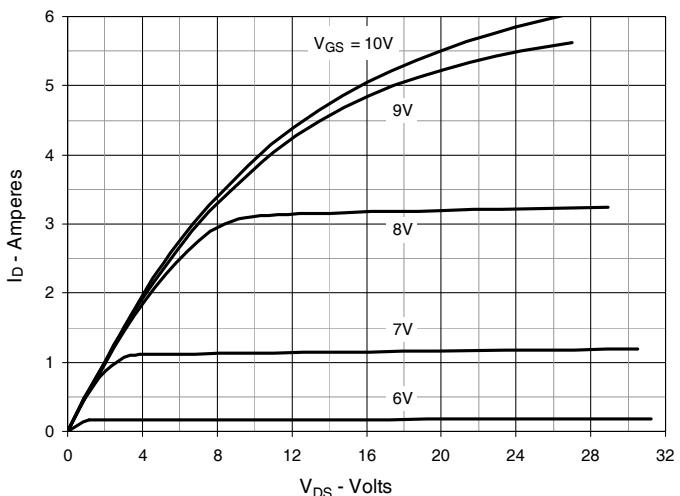
IXYS Reserves the Right to Change Limits, Test Conditions, and Dimensions.

IXYS MOSFETs and IGBTs are covered by one or more of the following U.S. patents: 4,835,592 4,931,844 5,049,961 5,237,481 6,162,665 6,404,065B1 6,683,344 6,727,585 7,005,734B2 7,157,338B2  
4,860,072 5,017,508 5,063,307 5,381,025 6,259,123B1 6,534,343 6,710,405B2 6,759,692 7,063,975B2  
4,881,106 5,034,796 5,187,117 5,486,715 6,306,728B1 6,583,505 6,710,463 6,771,478B2 7,071,537

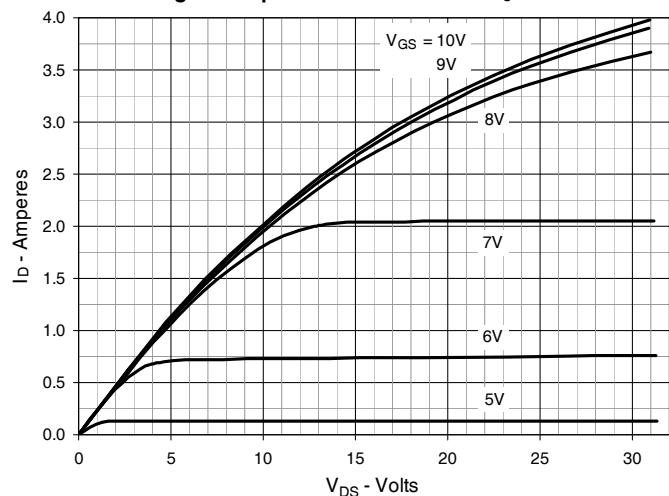
**Fig. 1. Output Characteristics @  $T_J = 25^\circ\text{C}$**



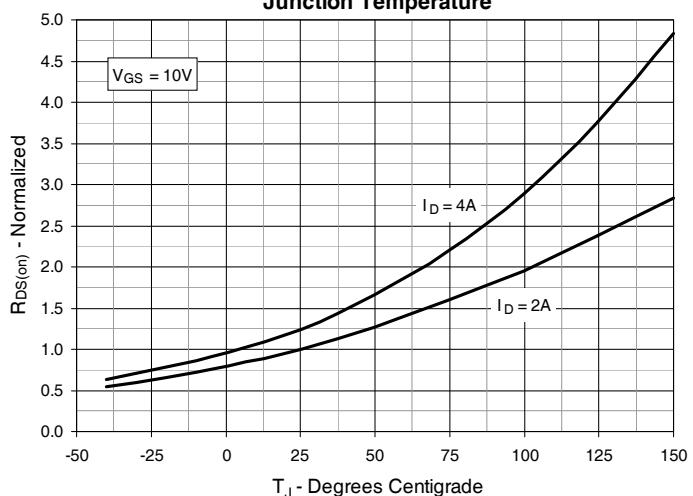
**Fig. 2. Extended Output Characteristics @  $T_J = 25^\circ\text{C}$**



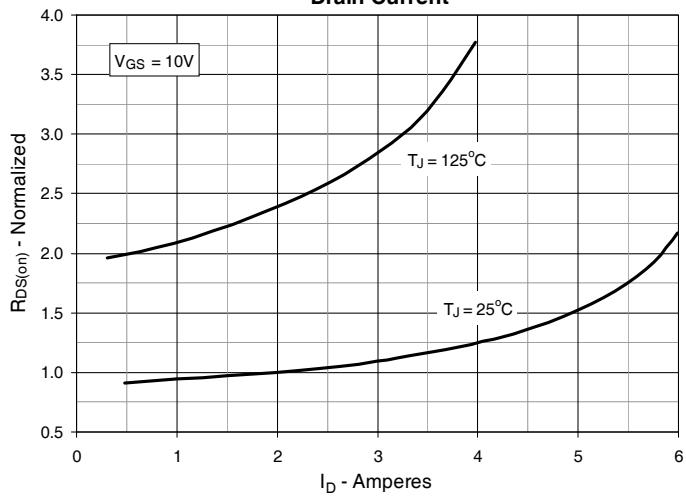
**Fig. 3. Output Characteristics @  $T_J = 125^\circ\text{C}$**



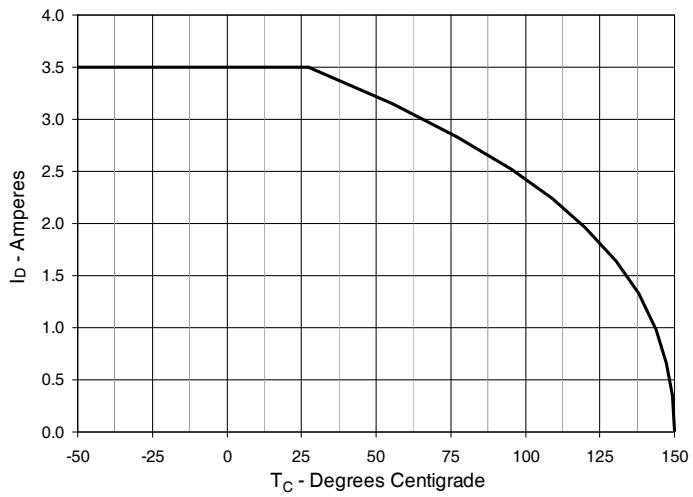
**Fig. 4.  $R_{DS(on)}$  Normalized to  $I_D = 2\text{A}$  Value vs. Junction Temperature**

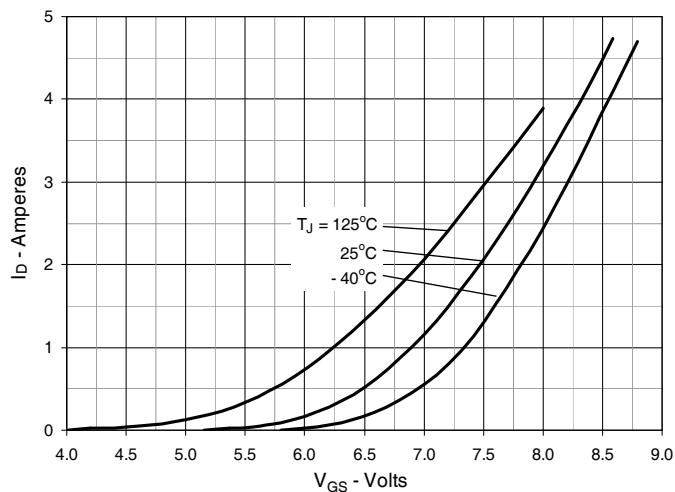
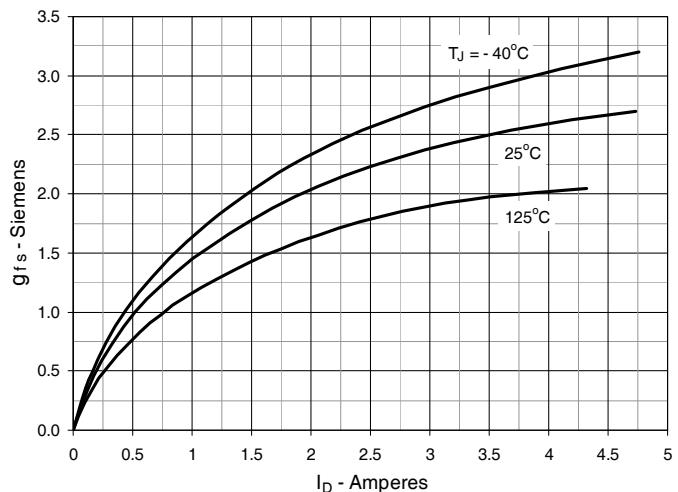
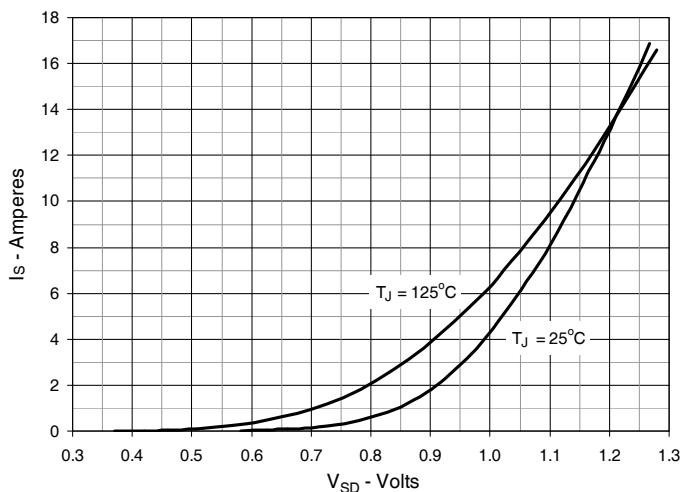
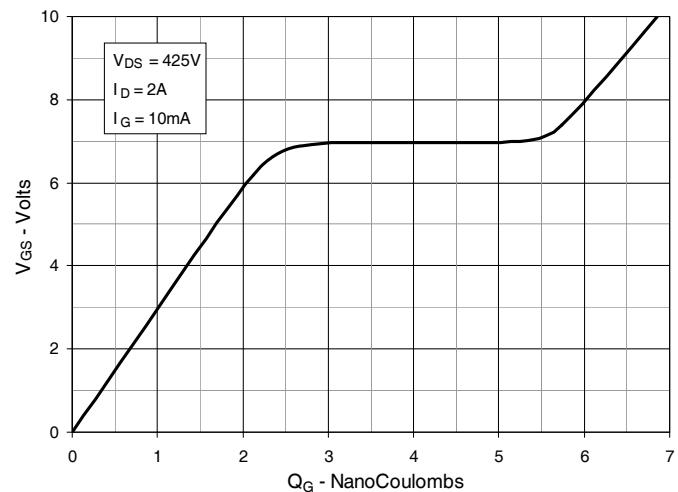
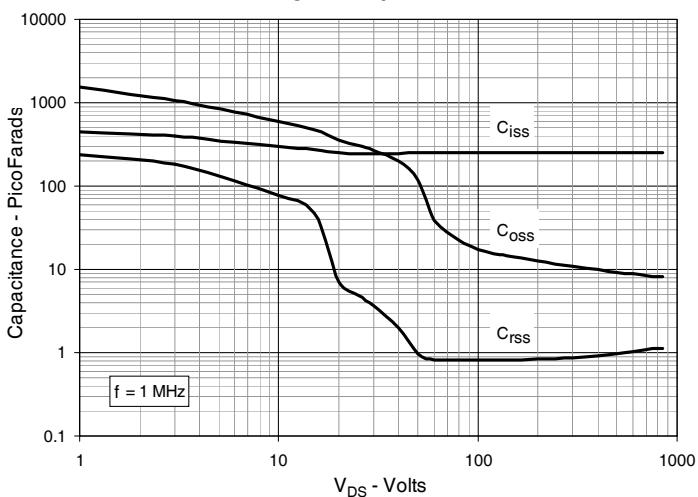
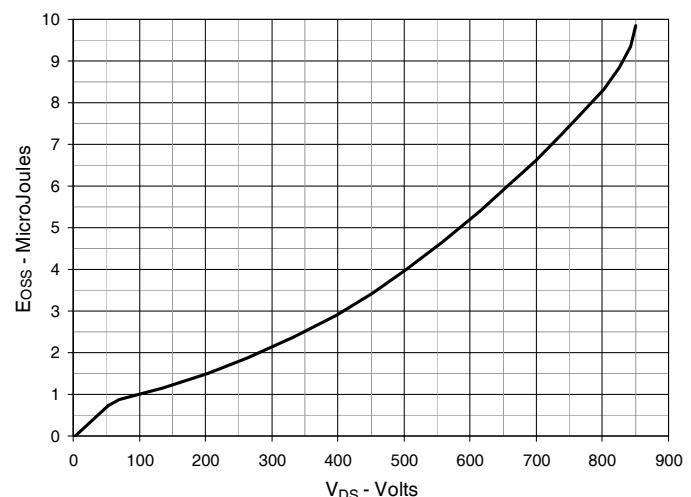


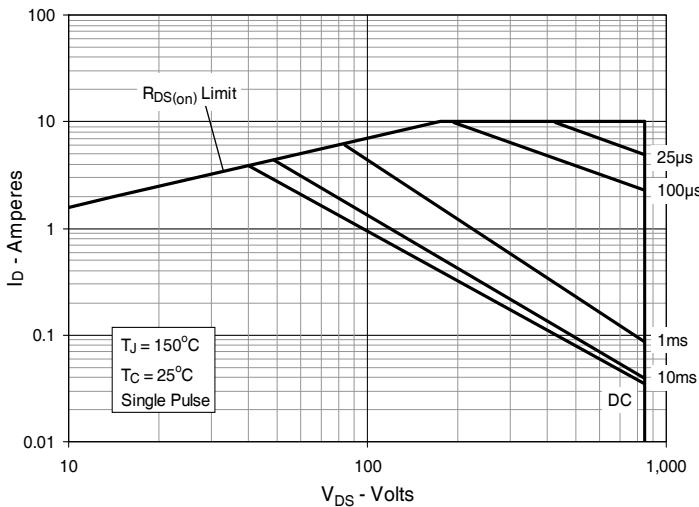
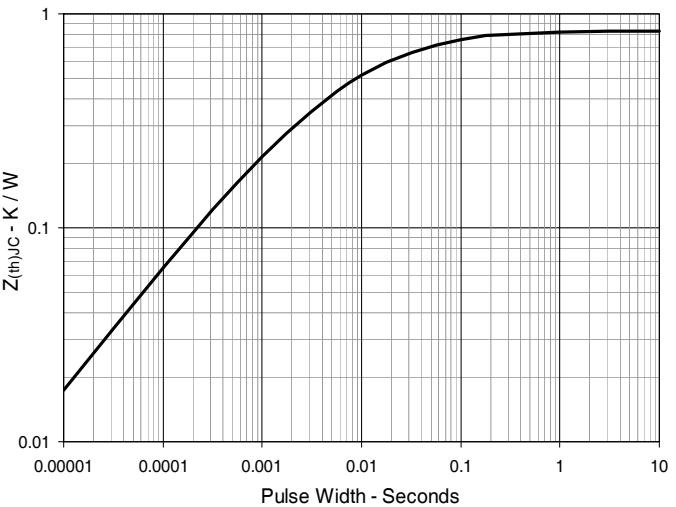
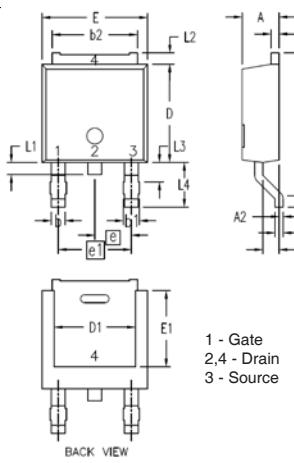
**Fig. 5.  $R_{DS(on)}$  Normalized to  $I_D = 2\text{A}$  Value vs. Drain Current**



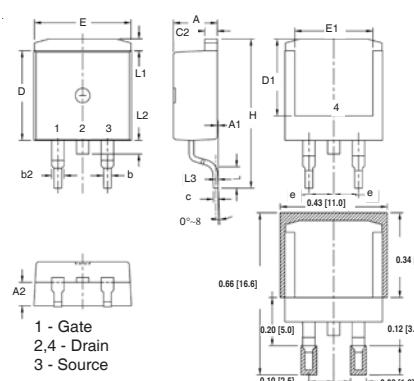
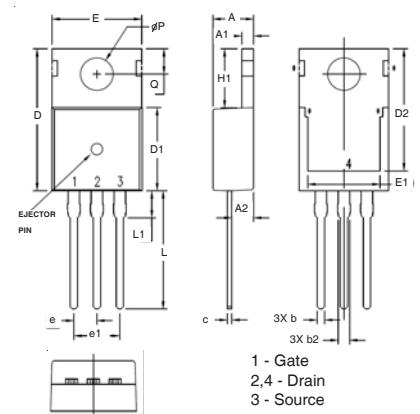
**Fig. 6. Maximum Drain Current vs. Case Temperature**



**Fig. 7. Input Admittance**

**Fig. 8. Transconductance**

**Fig. 9. Forward Voltage Drop of Intrinsic Diode**

**Fig. 10. Gate Charge**

**Fig. 11. Capacitance**

**Fig. 12. Output Capacitance Stored Energy**


**Fig. 13. Forward-Bias Safe Operating Area**

**Fig. 14. Maximum Transient Thermal Impedance**

**TO-252 Outline**


SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.086	.094	2.19	2.38
A1	.035	.045	0.89	1.14
A2	0	.004	0	0.10
b	.025	.035	0.64	0.89
b1	.030	.045	0.76	1.14
b2	.205	.215	5.21	5.46
c	.018	.023	0.46	0.58
c1	.018	.023	0.46	0.58
D	.235	.245	5.97	6.22
D1	.170	.205	4.32	5.21
E	.250	.265	6.35	6.73
E1	.170	.205	4.32	5.21
e	.090 BSC		2.28 BSC	
e1	.180 BSC		4.57 BSC	
H	.370	.410	9.40	10.42
L	.020	.040	0.51	1.02
L1	.025	.040	0.64	1.02
L2	.024	.036	0.60	0.90
L3	.045	.060	1.15	1.52
L4	.100	.115	2.54	2.92

**TO-263 Outline**

**TO-220 Outline**


SYM	INCHES		MILLIMETER	
	MIN	MAX	MIN	MAX
A	.170	.185	4.30	4.70
A1	.000	.008	0.00	0.20
A2	.091	.098	2.30	2.50
b	.028	.035	0.70	0.90
b2	.046	.060	1.18	1.52
C	.018	.024	0.45	0.60
C2	.049	.060	1.25	1.52
D	.340	.370	8.63	9.40
D1	.300	.327	7.62	8.30
E	.380	.410	9.65	10.41
E1	.270	.330	6.86	8.38
(E)	.100 BSC		2.54 BSC	
H	.580	.620	14.73	15.75
L	.075	.105	1.91	2.67
L1	.039	.060	1.00	1.52
L2	—	.070	—	1.77
(L3)	.010 BSC		0.254 BSC	

SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.169	.185	4.30	4.70
A1	.047	.055	1.20	1.40
A2	.079	.106	2.00	2.70
b	.024	.039	0.60	1.00
b2	.045	.057	1.15	1.45
c	.014	.026	0.35	0.65
D	.587	.626	14.90	15.90
D1	.335	.370	8.50	9.40
(D2)	.500	.531	12.70	13.50
E	.382	.406	9.70	10.30
(E1)	.283	.323	7.20	8.20
e	.100 BSC		2.54 BSC	
e1	.200 BSC		5.08 BSC	
H1	.244	.268	6.20	6.80
L	.492	.547	12.50	13.90
L1	.110	.154	2.80	3.90
ØP	.134	.150	3.40	3.80
Q	.106	.126	2.70	3.20